

Technical details – FR4 – Standard

Parameter	Technical descriptions	Remarks
Basic material	FR4 TG130 - TG170, CEM 1, CEM 3, Rogers, Teflon, Polyimide	
Layer count	1 - 28 layers	
Board thickness	0,15 mm - 4,5 mm	range of thickness depending on the number of layers
Copper	17 - 385 µm	0,5 oz – 11 oz
Size of circuit boards	600 x 1800 mm	
Minimum size of drilling diameter	mechanical: 0,2 mm lasered: 0,075 mm	Diameter from 6 mm to be milled.
Aspect ratio	1 : 12	
Line/Space	75 µm / 75 µm	
Solder mask	Taiyo, Tamura, Probimer, Imagecure	photosensitive lacquers in different colors
Surfaces	HAL-LF, Imm. NiAu, Imm. Tin, Imm. Silver, OSP, galvanic NiAu	
Printing	silk screen, strip varnish, carbon varnish, via filling	silk screen in white, yellow, black, red, blue, green
Contour	scribing, milling, stamping, beveling, countersinking, drilling	scribe slot 30°, chamber-bevel with 20°, 30° or 45°
Quality control	production according to IPC, AOI, E-test, micro-section, Initial sample testing	test voltage 150 to 250 V, inspection according to netlist is possible
Further technical potential	blind vias, buried vias, controlled impedance	

Technological specifics	on request
--------------------------------	------------

Stand: December 2015